



Intelligent Digital Twins: Trends and Applications in the Human-Centered Manufacturing Context

Guest Editors:

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Deadline for manuscript
submissions:

closed (30 April 2023)

Message from the Guest Editors

Dear Colleagues,

We invite authors to submit scientific papers that approach the aspects of integrating simulation, continuous/discrete optimization, human factors, and decision support models based on simulation and distributed intelligence into the digital twin of manufacturing and logistics systems. The topics include, but are not limited to:

- Definition of the role of simulation for digital twins in manufacturing and logistics
- Digital twin maturity model
- Human factors and human digital twins
- Real-time execution of simulation models for digital twin implementation
- Digital twin synchronization with the real manufacturing/logistics system counterpart
- Digital twin for decision support in production and logistics
- Distributed and Edge Intelligence
- Simulation-based digital twins
- Verification and validation of simulation models in digital twins
- Integration of Simulation with Virtual, Mixed and Augmented Reality for Digital Twin Applications
- Digital twin of stochastic production environments



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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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